

Title (en)

BLISTER PACKAGE AND METHOD OF MANUFACTURE

Title (de)

BLISTERVERPACKUNG UND VERFAHREN ZUR DEREN HERSTELLUNG

Title (fr)

EMBALLAGE-COQUE ET SON PROCEDE DE FABRICATION

Publication

**EP 3529164 B1 20210310 (EN)**

Application

**EP 17797818 A 20171030**

Priority

- US 201615341497 A 20161102
- US 2017058993 W 20171030

Abstract (en)

[origin: US10501248B2] Blister package having a novel pull tab construction that enables opening of each individual product cavity of the blister package. The pull tab is formed by breaking off a portion of a base substrate along a notched line that includes a series elongated severed portions extending completely through the thickness of the base substrate, separated by the unsevered (connected) portions. The notched line can be formed in the same mold that is used to form the recessed product cavity of the base substrate, thereby reducing the number of manufacturing steps and equipment, resulting in a significant cost savings during manufacture. The new notch line configuration eliminates the problems of the prior art with score depth achievement and consistency, while providing a reliable breakable line, and enable less brittle (non-PVC) polymers to be used. It also eliminates the problem with knife wear that prevented score depth achievement and consistency with non-PVC materials.

IPC 8 full level

**B65D 75/32** (2006.01); **B65D 75/58** (2006.01)

CPC (source: EP US)

**A61J 1/035** (2013.01 - US); **B65B 3/022** (2013.01 - US); **B65B 7/16** (2013.01 - US); **B65B 51/10** (2013.01 - US); **B65B 61/182** (2013.01 - US); **B65D 65/38** (2013.01 - US); **B65D 75/326** (2013.01 - EP US); **B65D 75/327** (2013.01 - EP US); **B65D 75/527** (2013.01 - US); **B65D 75/58** (2013.01 - EP US); **B65D 75/5816** (2013.01 - US); **B65D 75/5855** (2013.01 - US)

Designated contracting state (EPC)

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DOCDB simple family (publication)

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